

18 November 2014

Mouser Electronics
1000 N. Main St.
Mansfield, Texas 76063

ATTN: Quality/Purchasing Manager

Subject: Change from solder to UNIMEC XH9890-6A epoxy die attach on Gunn diodes

PCN #: PCN-00686

Dear Valued Customer:

M/A-COM Technology Solutions has a goal of providing the highest quality products with the highest level of service in terms of delivery. In alignment with this goal and to avoid potential interruptions in supply, we are pleased to announce a change from the use of solder preforms for die attach to an epoxy die attach process. In accordance with M/A-COM Technology Solutions' customer notification policy, you are receiving this notice because you have purchased one or more of the following products in the previous two years.

MACS-007801-0M1R16	MACS-007801-0M1RV2	MACS-007802-0M1RL6	MACS-007802-0M1RSF
MACS-007801-0M1R17	MACS-007801-0M1RV3	MACS-007802-0M1RL7	MACS-007966-0M1R39
MACS-007801-0M1RM0	MACS-007802-0M1R1B	MACS-007802-0M1RP5	MACS-007801-0M1RM7
MACS-007801-0M1RM3	MACS-007802-0M1R1C	MACS-007802-0M1RP6	MACS-007802-0M1RL4
MACS-007801-0M1RMF	MACS-007802-0M1R1D	MACS-007802-0M1RP7	MACS-007802-0M1RRF
MACS-007801-0M1RMR	MACS-007802-0M1R25	MACS-007802-0M1RP8	MACS-007802-0M1RS5
MACS-007801-0M1RV0	MACS-007802-0M1RB0	MACS-007802-0M1RS0	MACS-007802-0M1RSR
206362-5	206362-7		

All specifications and standards remain unchanged. This change will not affect form, fit, function or reliability. Details of the change are listed on the following page.

Sincerely,

Loren Reifsteck
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PCN Number:	PCN-00686	PCN Date:	18-November2014
Title:	Change from solder to UNIMEC XH9890-6A epoxy die attach on Gunn diodes		
Proposed 1st Ship Date:	01-February-2015	Estimated Sample Availability:	Contact factory
Change Type:			
Assembly Site	Design	Electrical Specification	
Test Site	Assembly Process	Mechanical Specification	
Test Process	Assembly Materials	X	Packing/Shipping/ Labeling
PCN Details			
Description of Change:			
MACOM is changing the die attach process from a solder preform to UNIMEC XH9890-6A epoxy. UNIMEC XH9890-6A is a low-temperature sintered die-attach paste using Metallo-Organic (MO) technology. This high thermal conductive paste does not require pressure while curing. This material has been developed for replacing eutectic solders offering the same thermal performance as AuSn solder.			
Reason for Change:			
The epoxy die attach is the assembly subcon's standard process. By moving to their standard process, we can help minimize any potential risk to the continuity of supply of parts to MACOM's customers.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
None			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
MACS-007801-0M1R16, MACS-007801-0M1RV2, MACS-007802-0M1RL6, MACS-007802-0M1RSF, MACS-007801-0M1R17, MACS-007801-0M1RV3, MACS-007802-0M1RL7, MACS-007966-0M1R39, MACS-007801-0M1RM0, MACS-007802-0M1R1B, MACS-007802-0M1RP5, MACS-007801-0M1RM7, MACS-007801-0M1RM3, MACS-007802-0M1R1C, MACS-007802-0M1RP6, MACS-007802-0M1RL4, MACS-007801-0M1RMF, MACS-007802-0M1R1D, MACS-007802-0M1RP7, MACS-007802-0M1RRF, MACS-007801-0M1RMR, MACS-007802-0M1R25, MACS-007802-0M1RP8, MACS-007802-0M1RS5, MACS-007801-0M1RV0, MACS-007802-0M1RB0, MACS-007802-0M1RS0, MACS-007802-0M1RSR, 206362-5, 206362-7			